



SPECIFICATION

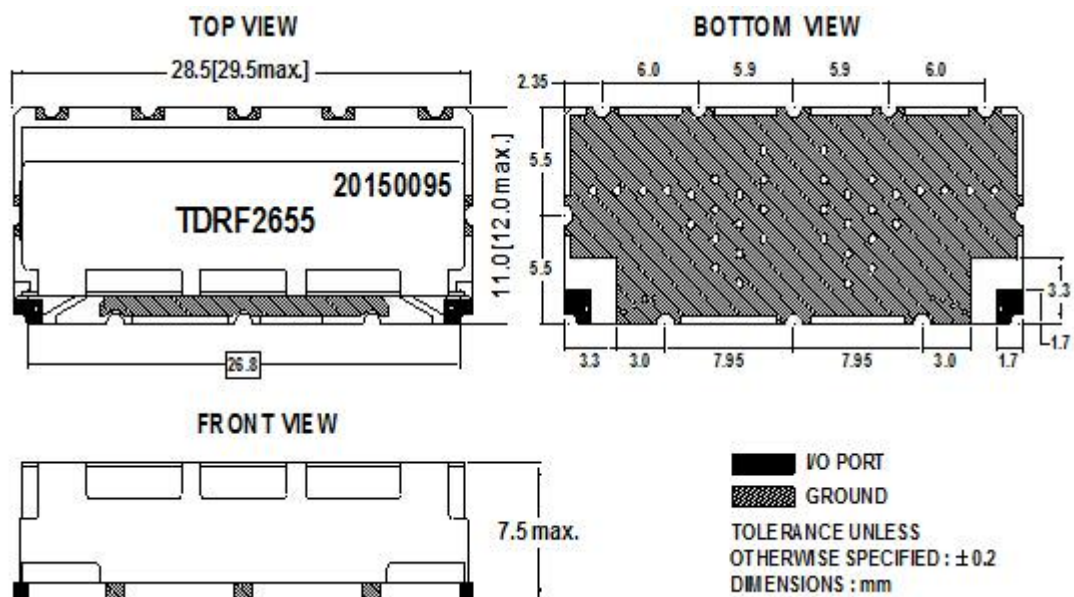
Part No.: _____
 Customer: _____
 Date: **2015-08-06**

Written by	Checked by	Approval
FL Lai	MY Chen	CK Chang

ELECTRICAL SPECIFICATIONS

ITEM	SPEC	UNIT
1 Center Frequency [fo]	2655.0	MHz
2 Bandwidth [BW]	Fo ±35.0 [2620.0~2690.0]	
3 Insertion Loss in BW	3.0	dB max
4 Ripple in BW	1.0	dB max
5 Return Loss in BW	13.0	dB min
6 Attenuation [Absolute Value]	40 dBc min @ 2500~2570 MHz 40 dBc min @ 791.0~960 MHz 40 dBc min @ 1710.0~2170.0 MHz	MHz
7 Input Power	3.0	W max
8 In/Out Impedance	50	ohm
9 Operation Temperature Range	-40 ~ +85	°C

DIMENSIONS



PERFORMANCE

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CH1 S22 REF 0.000 dB LOG MAG 5.000 dB/5.000 dB/

2.655GHz 500MHz

CH4 S33 REF 0.000 dB LOG MAG 10.000 dB/5.000 dB/

2.655GHz 500MHz

COLOR SCHEME

SCHEME-1

SCHEME-2

SCHEME-3

SCHEME-4

SCHEME-5

SCHEME-6

Return

CH2 MARKER LIST

1	2.655000	0000	GH	-19.159	00000000
2	2.655000	0000	GH	-19.159	00000000
3	2.655000	0000	GH	-19.159	00000000
4	2.655000	0000	GH	-19.159	00000000
5	2.655000	0000	GH	-19.159	00000000
6	2.655000	0000	GH	-19.159	00000000
7	2.655000	0000	GH	-19.159	00000000
8	2.655000	0000	GH	-19.159	00000000

CH4 MARKER LIST

1	2.655000	0000	GH	-1.818	00000000
2	2.655000	0000	GH	-1.818	00000000
3	2.655000	0000	GH	-1.818	00000000
4	2.655000	0000	GH	-1.818	00000000
5	2.655000	0000	GH	-1.818	00000000
6	2.655000	0000	GH	-1.818	00000000
7	2.655000	0000	GH	-1.818	00000000
8	2.655000	0000	GH	-1.818	00000000

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CH1 S22 LOG MAG REF 0.000 dB 5.000 dB/

CH2 S32 LOG MAG REF 0.000 dB 10.000 dB/

CH4 S33 LOG MAG REF 0.000 dB 5.000 dB/

START 2.2MHz [10.00 dBm] STOP 2.2GHz

BITMAP FILE

SAVE TO DISK

COMPRESSION ON OFF

TRUNCATE ON OFF

Return

1: 791.000MHz -0.106 dB

2: 960.000MHz -0.104 dB

3: 1.710 000GHz -0.388 dB

4: 2.170 000GHz -14.418 dB

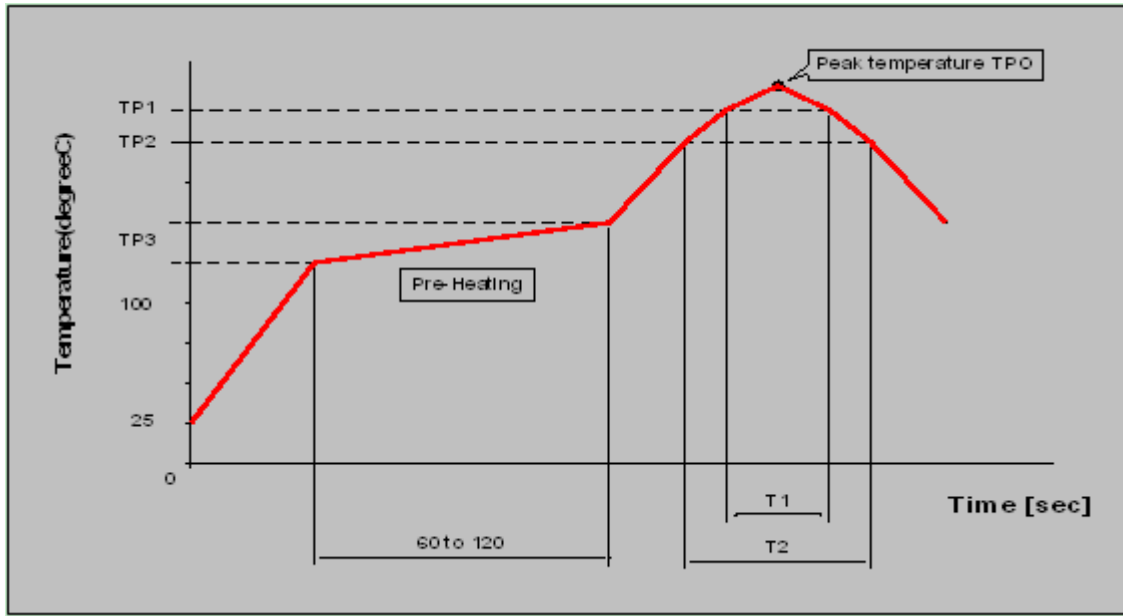
1: 791.000MHz -0.090 dB

2: 960.000MHz -77.452 dB

3: 1.710 000GHz -67.617 dB

4: 2.170 000GHz 65.215 dB

SOLDERING CONDITION



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

Reflow standard condition	TPO (°C)	TP1 (°C)	T1 (s)	TP2 (°C)	T2 (s)	TP3 (°C)
Sn-3Ag-0.5 solder	245+/-5	220	30 to 60	—	—	150 to 130
Test condition of reflow teat resistance	260+5/-0	240	20	220	70	150 to 130